A new Special Issue *Mechanical Engineering and Applications on Semiconductor Industry* (http://www.ijmea.org/sinfo/220031) has been launched in *International Journal of Mechanical Engineering and Applications* (http://www.ijmea.org). This Special Issue intends to collect research achievements concerning Semiconductor Industry. Novel insights as well as fundamental research on the topics are warmly welcomed. Your submissions along with your ingenious works are expected.

**Lead Guest Editor**

Lead Guest Editor: Jinfeng Wang  
Affiliation: Engineering, Cabot Microelectronics, Aurora, USA

**Paper Submission**

Potential authors are humbly requested to submit an electronic copy of their complete manuscript via http://www.ijmea.org/submission

**Topics of Interest Include (but not limited to):**

- Mechanical design for silicon chips  
- Mechanical design and challenges for next generation devices  
- AI and clean energy trend and requirement for mechanical engineering

**Important Dates**

- Submission Deadline: **Feb. 20, 2020**  
- Publication Deadline: **Apr. 20, 2020**

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For scholars who have intention to join the special issue as guest editor, please check out the link below:  
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